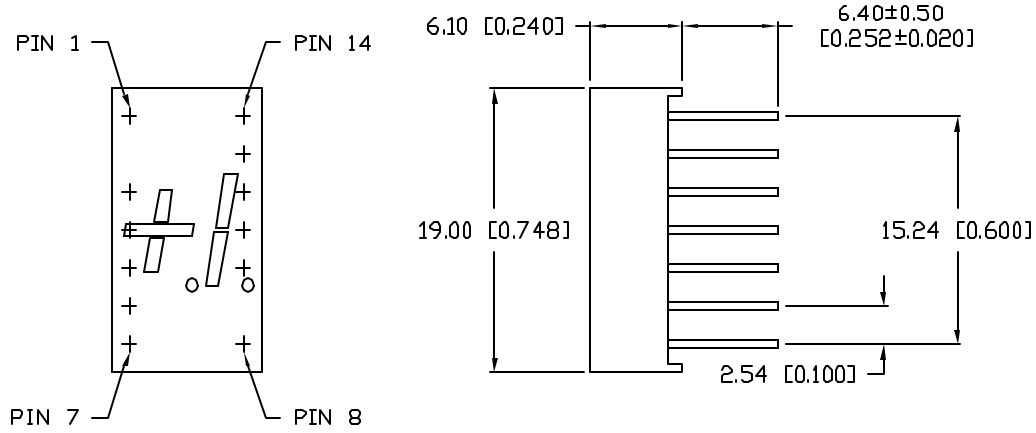


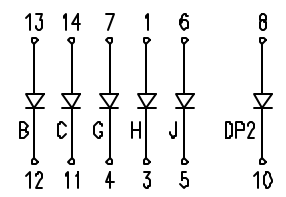
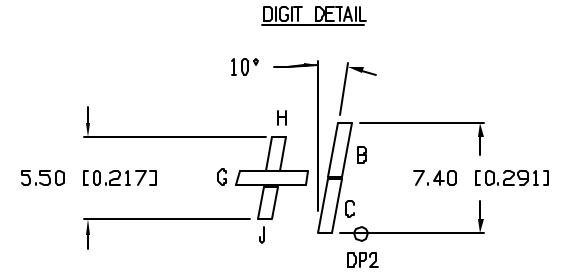
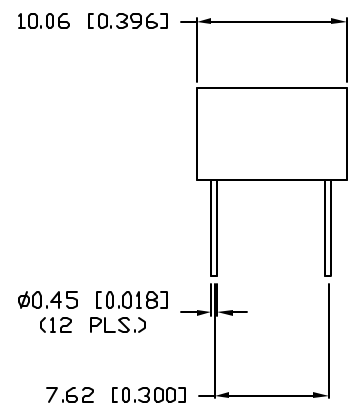
UNCONTROLLED DOCUMENT

| | | |
|-----------------------------------|-------------------------------------|------|
| PART NUMBER LDF-U3004RI | | REV. |
| REV. | E.C.N. NUMBER AND REVISION COMMENTS | DATE |



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|-----------------|----------------------|-----------|-----|----------------|----------------------|
| PEAK WAVELENGTH | | 635 (RED) | | nm | |
| FORWARD VOLTAGE | | 2.0 | 2.5 | V_f | |
| REVERSE VOLTAGE | 5.0 | | | V_r | $I_f=100\mu\text{A}$ |
| AXIAL INTENSITY | | 5000 | | μcd | $I_f=10\text{mA}$ |
| EMITTED COLOR: | RED | | | | |
| FACE COLOR: | GRAY | | | | |
| SEGMENT COLOR: | MILKY WHITE DIFFUSED | | | | |



NO PIN: 2 AND 9

LIMITS OF SAFE OPERATION AT 25°C PER DIE

| PARAMETER | MAX | UNITS |
|--------------------------|------------|------------|
| PEAK FORWARD CURRENT* | 150 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 105 | mW |
| DERATE FROM 25°C | -1.2 | mW/°C |
| OPERATING, STORAGE TEMP. | -40 TO +85 | °C |
| SOLDERING TEMP. | +260 | °C |
| 2.0mm FROM BODY | | 3 SEC. MAX |

* $t < 10\mu\text{s}$

UNCONTROLLED DOCUMENT
*UNLESS OTHERWISE SPECIFIED TOLERANCE IS $\pm 0.25\text{mm}$ (± 0.010)

| | |
|------|-----------------------------------|
| REV. | PART NUMBER LDF-U3004RI |
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LUMEX INCORPORATED
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PALATINE, ILLINOIS 60067
PHONE: 1-847-359-2790
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0.30" SINGLE DIGIT OVERFLOW DISPLAY,
635nm RED CHIPS, GRAY FACE, WHITE DIFFUSED SEGMENTS,
DIRECT DRIVE, RIGHT DECIMAL POINT.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

| | | | |
|--------------------|-------------|--------------|----------------|
| DRAWN BY: SS/DU | CHECKED BY: | APPROVED BY: | DATE: 10-28-99 |
| | | | PAGE: 1 OF 1 |
| | | | SCALE: N/A |